- 1. (withdrawn) An IC test apparatus comprising:
 - a. a rigid support member having an opening therein,
 thereby defining a peripheral edge around the opening,
 - a polymer membrane attached to the rigid support
 member and having a center portion covering the opening,
 - c. a probe contact array on the center portion of the polymer membrane,
 - d. a wafer platform,
 - e. means for depressing the center portion of the polymer membrane toward the wafer platform,
 - f. at least one reference IC chip located adjacent to the peripheral edge of the opening in the rigid support,
 - g. interconnection means interconnecting the reference IC chip and the probe contact array.
- 2. (withdrawn) The apparatus of claim 1 wherein the reference IC chip includes at least one LC circuit.
- 3. (withdrawn) The apparatus of claim 1 wherein the opening has four sides, the apparatus further comprising a first reference IC chip located adjacent one side and a second IC reference chip located adjacent another side.

- 4. (withdrawn) The apparatus of claim 1 further including at least one reference component attached to the polymer membrane adjacent to the probe contact array.
- 5. (withdrawn) The apparatus of claim 4 wherein the reference component comprises an LC circuit.
- 6. (previously presented) An IC test apparatus comprising:
 - a. a rigid support member having an opening therein,
 thereby defining a peripheral edge around the opening,
 - a polymer membrane attached to the rigid support
 member and having a center portion covering the opening,
 - c. a probe contact array on the center portion of the polymer membrane,
 - d. a wafer platform,
 - e. means for depressing the center portion of the polymer membrane toward the wafer platform,
 - f. at least one reference <u>circuit</u> component attached to the polymer membrane and located adjacent to the probe contact array, and

- g. interconnection means address runners interconnecting the reference <u>circuit</u> component and the probe contact array.
- 7. (previously presented) The apparatus of claim 6 wherein the reference <u>circuit</u> component comprises an LC circuit.
- 8. (previously presented) The apparatus of claim 7 wherein the reference <u>circuit</u> component <u>comprises</u> is part of a passive IC chip.
- 9. (previously presented) The apparatus of claim 6 wherein the reference <u>circuit</u> component <u>comprises</u> is part of a digital test circuit.
- 10. (withdrawn) An IC test apparatus comprising:
 - a. a rigid support member having an opening therein,
 thereby defining a peripheral edge around the opening,
 - a polymer membrane attached to the rigid support
 member and having a center portion covering the opening,
 - c. a probe contact array on the center portion of the polymer membrane,

- d. a wafer platform,
- e. means for depressing the center portion of the polymer membrane toward the wafer platform,
- f. a reference IC chip attached to the polymer membrane and located adjacent to the probe contact array, and
- g. interconnection means interconnecting the reference component and the probe contact array.
- 11. (withdrawn) The apparatus of claim 10 wherein the reference IC chip comprises a passive IC chip.
- 12. (withdrawn) The apparatus of claim 10 wherein the reference IC chip comprises an active IC chip.
- 13. (canceled)
- 14. (canceled)
- 15. (canceled)
- 16. (canceled)

- 17. (withdrawn) A method for testing an IC wafer comprising:
 - a. mounting a probe membrane on a rigid support
 member, the rigid support member having an opening
 therein, and the probe membrane attached to the rigid
 support member with a center portion thereof covering the
 opening, the center portion including a probe contact array,
 and a reference IC,
 - b. mounting a wafer under test on a platform under the opening,
 - c. moving the center portion of the probe membrane so that the probe contact array comes into contact with the wafer under test, and
 - d. passing electrical test signals between I/Os on the wafer under test and a test circuit.
- 18. (withdrawn) The method of claim 17 wherein the I/Os on the wafer under test and the reference IC comprise a fully functional system.
- 19. (canceled)